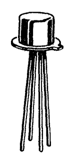
2N5031 (SILICON)
2N5032

NPN SILICON RF SMALL-SIGNAL TRANSISTORS

. . . designed primarily for use in high-gain, low-noise, small-signal amplifiers in military and industrial equipment. Suitable for use in video wideband and general high-frequency amplifier applications of 50 to 1000 MHz.

- Low Noise Figure –
  NF = 2.5 dB (Max) @ f = 450 MHz (2N5031)
- High Power Gain –
  G_{pe} = 17 dB (Typ) @ f = 450 MHz
- High Current-Gain–Bandwidth Product –
  f_T = 1000 MHz (Min) @ I_C = 5.0 mAdc

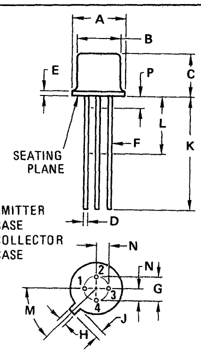
NPN SILICON
RF SMALL-SIGNAL
TRANSISTORS



*MAXIMUM RATINGS

Rating	Symbol	Value	Unit
Collector-Emitter Voltage	V_{CEO}	10	Vdc
Collector-Base Voltage	V_{CB}	15	Vdc
Emitter-Base Voltage	V_{EB}	3.0	Vdc
Collector Current – Continuous	I_C	20	mAdc
Total Device Dissipation @ T_A = 25°C Derate above 25°C	P_D	200 1.14	mW mW/°C
Operating and Storage Junction Temperature Range	T_J, T_{stg}	-65 to +200	°C

*Indicates JEDEC Registered Data.



STYLE 10
PIN 1. EMITTER
2. BASE
3. COLLECTOR
4. CASE

DIM	MILLIMETERS MIN	MILLIMETERS MAX	INCHES MIN	INCHES MAX
A	5.31	5.84	0.209	0.230
B	4.52	4.95	0.178	0.195
C	4.32	5.33	0.170	0.210
D	0.41	0.53	0.016	0.021
E	–	0.76	–	0.030
F	0.41	0.48	0.016	0.019
G	2.54 BSC		0.100 BSC	
H	0.91	1.17	0.036	0.046
J	0.71	1.22	0.028	0.048
K	12.70	–	0.500	–
L	6.35	–	0.250	–
M	45° BSC		45° BSC	
N	1.27 BSC		0.050 BSC	
P	–	1.27	–	0.050

ALL JEDEC dimensions and notes apply

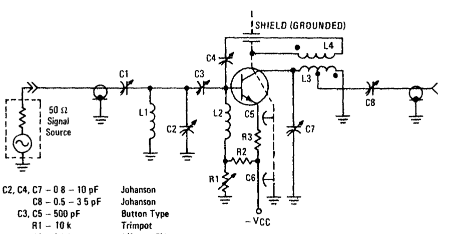
CASE 20-03
TO-72

ELECTRICAL CHARACTERISTICS (T_A = 25°C unless otherwise noted)

Characteristic	Symbol	Min	Typ	Max	Unit
OFF CHARACTERISTICS					
*Collector-Emitter Breakdown Voltage (I_C = 1.0 mAdc, I_B = 0)	BV_{CEO}	10	–	–	Vdc
*Collector-Base Breakdown Voltage (I_C = 0.01 mAdc, I_E = 0)	BV_{CBO}	15	–	–	Vdc
*Emitter-Base Breakdown Voltage (I_E = 0.01 mAdc, I_C = 0)	BV_{EBO}	3.0	–	–	Vdc
*Collector Cutoff Current (V_{CB} = 6.0 Vdc, I_E = 0)	I_{CBO}	–	1.0	10	nAdc
ON CHARACTERISTICS					
*DC Current Gain (I_C = 1.0 mAdc, V_{CE} = 6.0 Vdc)	h_{FE}	25	–	300	–
Collector-Emitter Saturation Voltage (I_C = 10 mAdc, I_B = 1.0 mAdc)	$V_{CE(sat)}$	–	0.35	–	Vdc
Base-Emitter Saturation Voltage (I_C = 10 mAdc, I_B = 5.0 mAdc)	$V_{BE(sat)}$	–	1.0	–	Vdc
DYNAMIC CHARACTERISTICS					
*Current-Gain–Bandwidth Product (I_C = 5.0 mAdc, V_{CE} = 6.0 Vdc, f = 100 MHz)	f_T	1000	–	3500	MHz
*Output Capacitance (V_{CE} = 6.0 Vdc, I_E = 0, f = 0.1 MHz)	C_{cb}	–	1.3	1.5	pF
Collector-Base Time Constant (I_C = 6.0 mAdc, V_{CE} = 6.0 Vdc, f = 31.8 MHz)	$r_b'C_c$	–	5.0	–	ps
*Noise Figure† (Figure 1) (I_C = 1.0 mAdc, V_{CE} = 6.0 Vdc, f = 450 MHz) 2N5031	NF	–	–	2.5	dB
2N5032		–	–	3.0	
FUNCTIONAL TEST					
*Common-Emitter Amplifier Power Gain† (Figure 1) (V_{CE} = 6.0 Vdc, I_C = 1.0 mAdc, f = 450 MHz)	G_{pe}	14	17	25	dB

*Indicates JEDEC Registered Data.
†Tuned for Minimum Noise.

FIGURE 1 – POWER GAIN AND NOISE FIGURE TEST CIRCUIT



C1, C2, C4, C7 – 0 8 – 10 pF Johanson
C8 – 0.5 – 3 5 pF Johanson
C3, C5 – 500 pF Button Type
R1 – 10 k Trimpot
R2 – 2 7 k 1/4 watt 5%
R3 – 1.0 k 1/4 watt 5%
L1 – 1/4" Brass Rod, Solder Plated, 1-1/8" long. Placed 5/8" from the socket and in parallel with the shield, which bisects the socket. The ungrounded side is soldered directly to the ungrounded side of C2.
L2 – 0 22 μH
L3 – 1/4" Brass Rod, Solder Plated, 1-1/2" long. Placed 1/2" from the socket and in parallel with shield, which bisects the socket. The ungrounded side is soldered directly to the ungrounded side of C7. Output tap is 15/16" from ground.
L4 – 1/2 Turn #16, 5/16" above L3 and 5/8" long, (over L3).

FIGURE 2 – COLLECTOR-BASE CAPACITANCE versus VOLTAGE

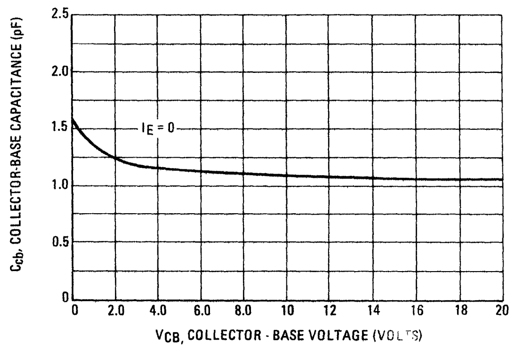


FIGURE 3 – CURRENT-GAIN–BANDWIDTH PRODUCT

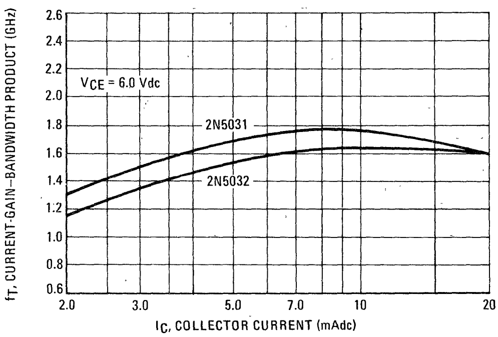


FIGURE 4 – S_{11} AND S_{22}

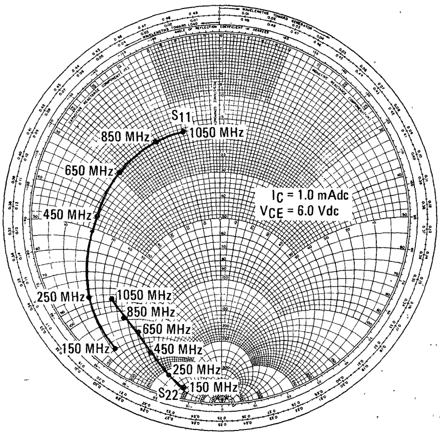


FIGURE 5 – S_{12}

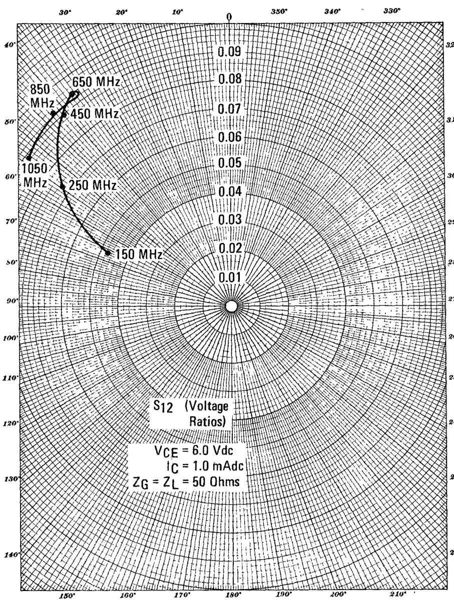


FIGURE 6 – S_{21}

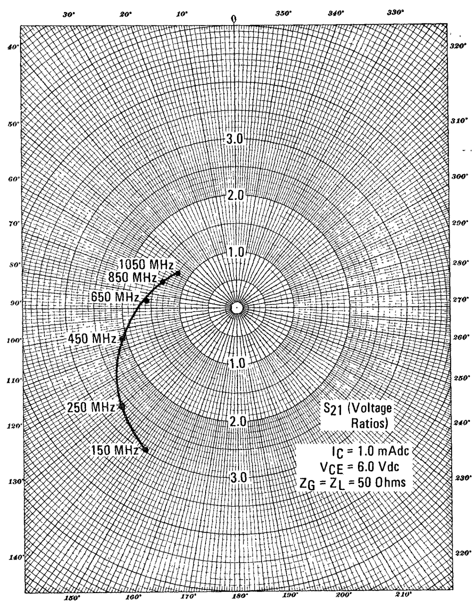


FIGURE 7 – NOISE FIGURE versus FREQUENCY

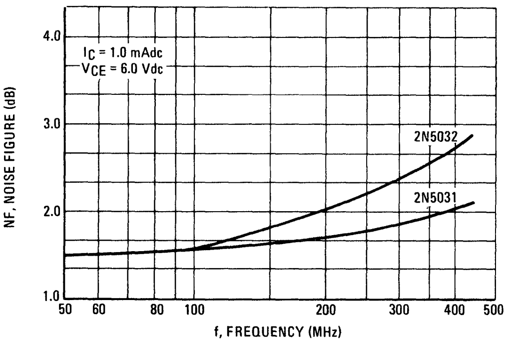


FIGURE 8 – POWER GAIN versus FREQUENCY

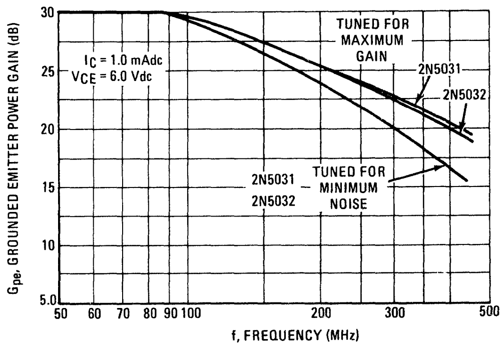


FIGURE 9 – INPUT ADMITTANCE versus FREQUENCY

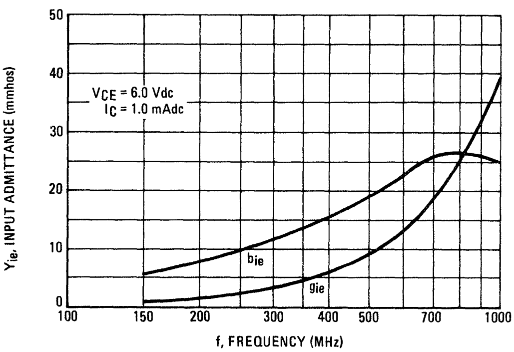


FIGURE 10 – OUTPUT ADMITTANCE versus FREQUENCY

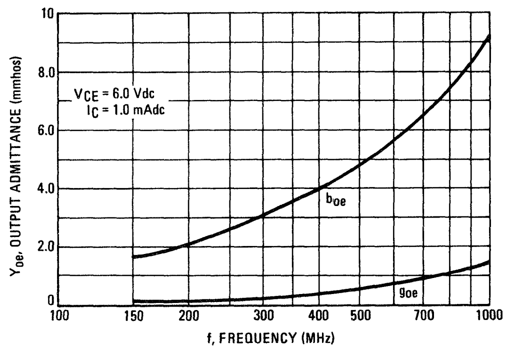


FIGURE 11 – FORWARD TRANSFER ADMITTANCE versus FREQUENCY

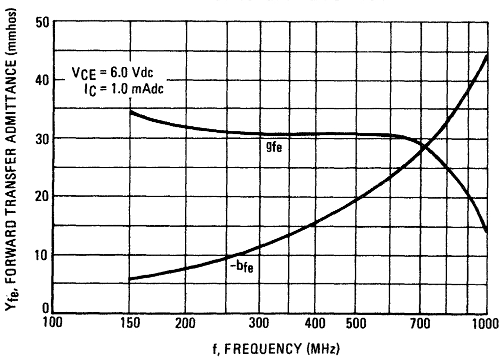


FIGURE 12 – REVERSE TRANSFER ADMITTANCE versus FREQUENCY